

SANYO Semiconductors

DATA SHEET

An ON Semiconductor Company



N-Channel Silicon MOSFET **General-Purpose Switching Device Applications**

Features

- ON-resistance $R_{DS}(on)1=5.2m\Omega$ (typ.)
- 1.8V drive.
- · Halogen free compliance.
- · Protection diode in

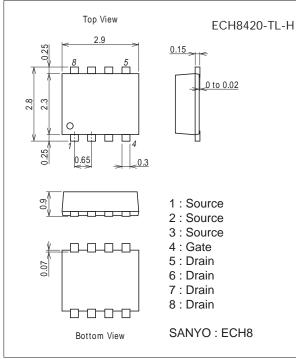
Specifications

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Conditions	Ratings	Unit
Drain-to-Source Voltage	VDSS		20	V
Gate-to-Source Voltage	VGSS		±12	V
Drain Current (DC)	ID		14	Α
Drain Current (Pulse)	IDP	PW≤10μs, duty cycle≤1%	50	Α
Allowable Power Dissipation	PD	When mounted on ceramic substrate (900mm ² ×0.8mm)	1.6	W
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-55 to +150	°C

Package Dimensions

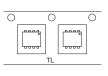
unit : mm (typ) 7011A-002



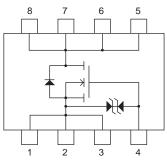
Product & Package Information

- Package : ECH8
- JEITA, JEDEC : -
- Minimum Packing Quantity : 3,000 pcs./reel

Packing Type : TL



Electrical Connection



Lot No.



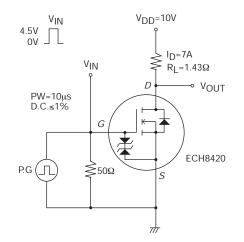
ZA

Marking

Electrical Characteristics at Ta=25°C

Deventer	Currele el		Ratings			1.1	
Parameter	Symbol	Conditions	min	typ	max	Unit	
Drain-to-Source Breakdown Voltage	V(BR)DSS	ID=1mA, VGS=0V	20			V	
Zero-Gate Voltage Drain Current	IDSS	V _{DS} =20V, V _{GS} =0V			1	μΑ	
Gate-to-Source Leakage Current	IGSS	V _{GS} =±8V, V _{DS} =0V			±10	μΑ	
Cutoff Voltage	V _{GS} (off)	V _{DS} =10V, I _D =1mA	0.4		1.3	V	
Forward Transfer Admittance	yfs VDS=10V, ID=7A			14.5		S	
	R _{DS} (on)1	ID=7A, VGS=4.5V		5.2	6.8	mΩ	
Static Drain-to-Source On-State Resistance	R _{DS} (on)2	ID=4A, VGS=2.5V		8	11.5	mΩ	
	R _{DS} (on)3	ID=2A, VGS=1.8V		15	22.5	mΩ	
Input Capacitance	Ciss			2430		рF	
Output Capacitance	Coss	V _{DS} =10V, f=1MHz		410		рF	
Reverse Transfer Capacitance	Crss			330		рF	
Turn-ON Delay Time	t _d (on)			21		ns	
Rise Time	tr			88		ns	
Turn-OFF Delay Time td(off)		See specified Test Circuit.		210		ns	
Fall Time	tf			115		ns	
Total Gate Charge	Qg			29		nC	
Gate-to-Source Charge	Qgs	V _{DS} =10V, V _{GS} =4.5V, I _D =14A		4.8		nC	
Gate-to-Drain "Miller" Charge	Qgd			8.7		nC	
Diode Forward Voltage	V _{SD}	IS=14A, VGS=0V		0.75	1.2	V	

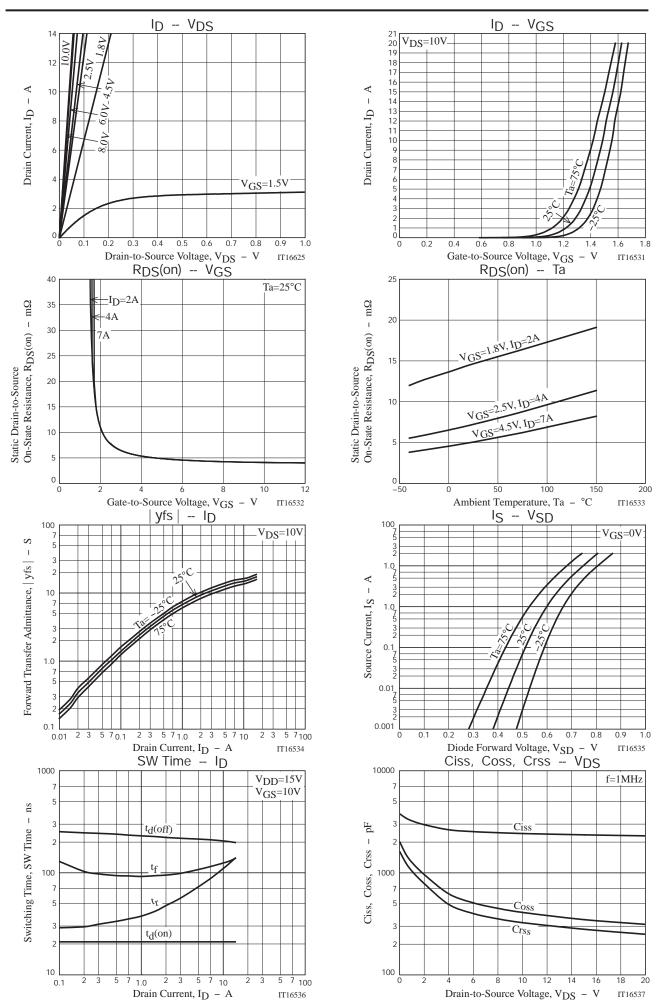
Switching Time Test Circuit

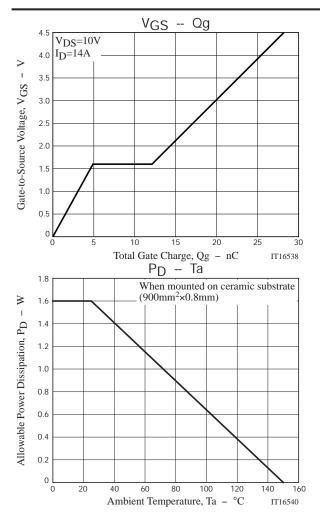


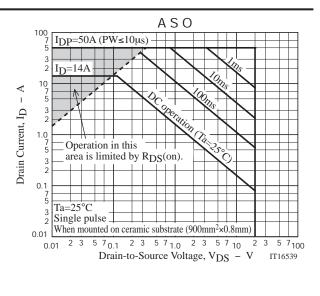
Ordering Information

Device Package		Shipping	memo	
ECH8420-TL-H	ECH8	3,000pcs./reel	Pb Free and Halogen Free	

ECH8420







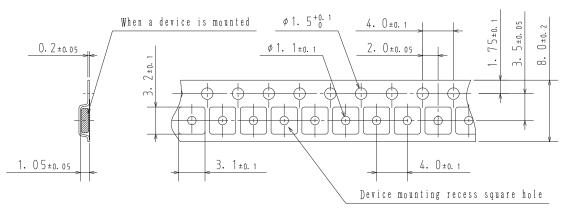
Embossed Taping Specification ECH8420-TL-H

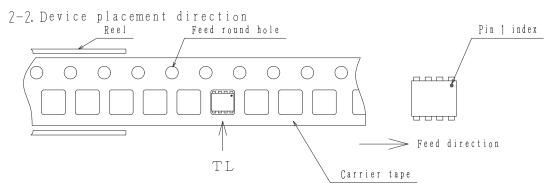
1. Packing Format

ECHO CFHO 3,000 70,000 70,000 1 Dimensions:mm (external) 183×72×185 Dimensions:mm (external) Packing method (unit:mm) Quartity Quantity Image: Comparison of a label 108 Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label Image: Comparison of a label	Package Name	Carrier Tape	Maximum Number of devices contained (pcs)			Packing format		
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Dimensions:mm (external) Dimensions:mm (external) 183×72×185 440×195×210 Add Ox 195×210 440×195×210 Packing method (unit:mm) Packing method Outer box label (unit:mm) Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and change in physical distribution process. Image: Construction of a label and the time of factory shipme the physical distribution process. Image: Construction of a label and the time of factory shipme the physical distribution process. Image: Constructin of	ECH8	CPH6	3,000	15,000	90,000	5 reels contained 6 inner boxes contained		
Reel label, Inner box label (un it :mm) Outer box label It is a label at the time of factory shipme The form of a label may change in physical distribution process. Packing method 69 108 Origin 90000000000 110000000000000000000000000		_				Dimensions:mm (external) Dimensions:mm (external)		
Packing method (unit:mm) It is a label at the time of factory shipme The form of a label may change in physical distribution process. Type No. 69 LOT No. (Unit:minimum minimum mini						183×72×185 440×195×210		
treatment of the terminal is lead free. Label JEITA Phase LEAD FREE 3 JEITA Phase 3A	Packing met	Type LOT Quan Orig	No. tity in	-> (P. -> (P. -> (Q. ->	(u: TYPE 0000C IIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIII	nner box label Outer box label nit:mm) Tis a label at the time of factory shipments. The form of a label may change in physical distribution process. 108 000000 TYPE CODE 000000 ************************************		

2. Taping configuration

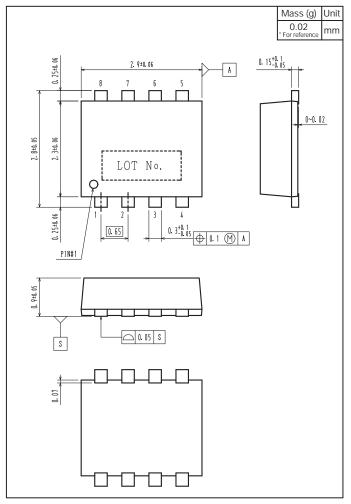
2-1. Carrier tape size (unit:mm)



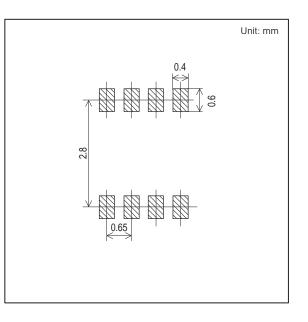


Those with pin 1 index on the feed hole side ·····TL

Outline Drawing ECH8420-TL-H



Land Pattern Example



Note on usage : Since the ECH8420 is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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